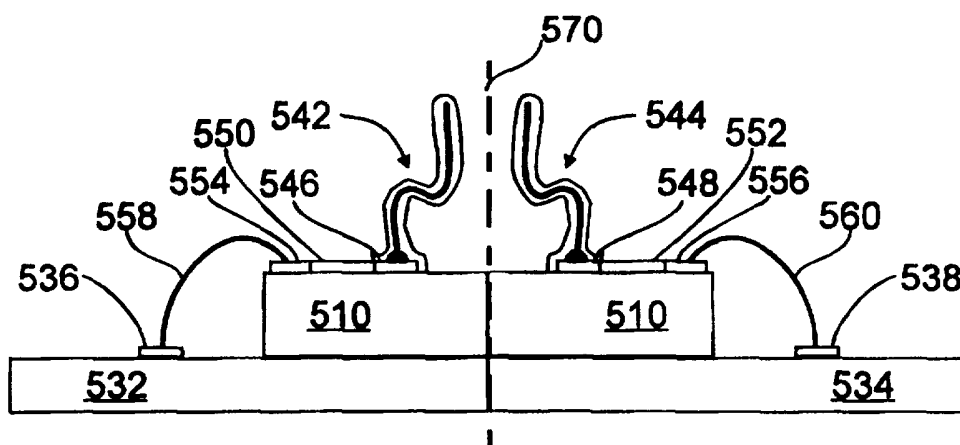




INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

<p>(51) International Patent Classification ⁶ : B05D 5/12, B23K 31/02, G01R 31/26, H01L 21/44, 23/48, 23/485, 23/49, 23/498, 23/50, H01R 9/09, 9/11, 43/02, H05K 1/11, 7/02</p>	<p>A3</p>	<p>(11) International Publication Number: WO 97/16866</p> <p>(43) International Publication Date: 9 May 1997 (09.05.97)</p>																				
<p>(21) International Application Number: PCT/US96/08328</p> <p>(22) International Filing Date: 28 May 1996 (28.05.96)</p> <p>(30) Priority Data:</p> <table border="0"> <tr> <td>08/452,255</td> <td>26 May 1995 (26.05.95)</td> <td>US</td> </tr> <tr> <td>08/526,246</td> <td>21 September 1995 (21.09.95)</td> <td>US</td> </tr> <tr> <td>08/533,584</td> <td>18 October 1995 (18.10.95)</td> <td>US</td> </tr> <tr> <td>08/554,902</td> <td>9 November 1995 (09.11.95)</td> <td>US</td> </tr> <tr> <td>PCT/US95/14909</td> <td>13 November 1995 (13.11.95)</td> <td>WO</td> </tr> </table> <p>(34) Countries for which the regional or international application was filed: US et al.</p> <table border="0"> <tr> <td>08/558,332</td> <td>15 November 1995 (15.11.95)</td> <td>US</td> </tr> <tr> <td>08/602,179</td> <td>15 February 1996 (15.02.96)</td> <td>US</td> </tr> </table> <p>(71) Applicant (for all designated States except US): FORMFAC-TOR, INC. [US/US]; 2130 Research Drive, Livermore, CA 94550 (US).</p> <p>(72) Inventors; and</p> <p>(75) Inventors/Applicants (for US only): KHANDROS, Igor, Y. [US/US]; 25 Haciendas Road, Orinda, CA 94563 (US). CHANG, Sung, Chul [KR/US]; 6706 Arrowwood Drive, Riverbank, CA 95367 (US). SMITH, William, D. [US/US]; 6270 Stoneridge Mall Road, C106, Pleasanton, CA 94588 (US).</p>	08/452,255	26 May 1995 (26.05.95)	US	08/526,246	21 September 1995 (21.09.95)	US	08/533,584	18 October 1995 (18.10.95)	US	08/554,902	9 November 1995 (09.11.95)	US	PCT/US95/14909	13 November 1995 (13.11.95)	WO	08/558,332	15 November 1995 (15.11.95)	US	08/602,179	15 February 1996 (15.02.96)	US	<p>(74) Agent: SUEOKA, Greg, T.; Fenwick & West, L.L.P., Suite 700, Two Palo Alto Square, Palo Alto, CA 94306 (US).</p> <p>(81) Designated States: AM, AT, AU, BB, BG, BR, BY, CA, CH, CN, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LT, LU, LV, MD, MG, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TT, UA, UG, US, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG).</p> <p>Published <i>With international search report.</i> <i>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i></p> <p>(88) Date of publication of the international search report: 19 June 1997 (19.06.97)</p>
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<p>(54) Title: CHIP INTERCONNECTION CARRIER AND METHODS OF MOUNTING SPRING CONTACTS TO SEMICONDUCTOR DEVICES</p>																						



(57) Abstract

A plurality of free-standing spring elements (512) are mounted to a surface (510a) of a carrier substrate (510). The carrier substrate (510) is mounted to a surface (502a) of a semiconductor device (502). Bond pads (504) of the semiconductor device are connected to the spring elements (512) by bond wires (520) extending between the bond pads (504) and terminals (516) associated with the spring elements. Alternatively, the carrier is flip-chip reflow soldered to the semiconductor device. The carrier substrate (510) is suitably mounted to one or more semiconductor devices (532, 534) prior to the semiconductor devices being singulated from a semiconductor wafer upon which they are formed. Resilience and compliance to effect pressure connections to the semiconductor device (502) are provided by the spring elements (512) extending from the carrier substrate (510), per se. Hence, the carrier substrate (510) suitably remains rigid with respect to the semiconductor device (502). The carrier substrate (510) is advantageously pre-fabricated, by mounting the spring elements (512) thereto prior to mounting the carrier substrate to the semiconductor device(s).

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INTERNATIONAL SEARCH REPORT

International application No.
PCT/US96/08328

A. CLASSIFICATION OF SUBJECT MATTER
 IPC(6) :Please See Extra Sheet.
 US CL :Please See Extra Sheet.
 According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED
 Minimum documentation searched (classification system followed by classification symbols)
 U.S. : Please See Extra Sheet.

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X ---- Y	US 5,414,298 A (GRUBE et al.) 09 MAY 1995, see entire document.	1, 3 - 5, 9, 19, 20,21,22, 23,24,32, 34-37, 41 and 44 ----- 8 and 33
X	US 3,842,189 A (SOUTHGATE) 15 OCTOBER 1974, see entire document.	34-37
X	US 5,346,861 A (KHANDROS et al.) 13 SEPTEMBER 1994, see entire document.	38 and 40
X	US 5,230,632 A (BAUMBERGER et al.) 27 JULY 1993, see entire document.	38-40

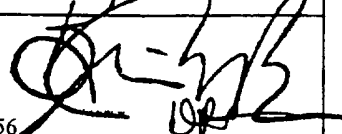
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Date of the actual completion of the international search: 20 APRIL 1997
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US CL :

29/827, 829, 832, 838, 840, 842, 843, 844, 850, 854, 881, 882, 884, 885; 174/52.1, 52.4; 228/179.1, 180.1, 180.21, 180.5; 257/666, 668, 672, 676, 677, 692, 696, 700, 735, 736, 741, 748, 750, 759, 779, 781, 784, 785; 324/537, 765; 361/760, 767-774, 776, 779, 783, 792-795, 807, 809; 427/96, 117, 118, 123, 126.1; 437/180, 182-184, 189, 192, 195, 203, 209, 220; 439/66, 68, 69, 81, 83, 85, 91

B. FIELDS SEARCHED

Minimum documentation searched

Classification System: U.S.

29/827, 829, 832, 838, 840, 842, 843, 844, 850, 854, 881, 882, 884, 885; 174/52.1, 52.4; 228/179.1, 180.1, 180.21, 180.5; 257/666, 668, 672, 676, 677, 692, 696, 700, 735, 736, 741, 748, 750, 759, 779, 781, 784, 785; 324/537, 765; 361/760, 767-774, 776, 779, 783, 792-795, 807, 809; 427/96, 117, 118, 123, 126.1; 437/180, 182-184, 189, 192, 195, 203, 209, 220; 439/66, 68, 69, 81, 83, 85, 91